

IN THE CLAIMS:

Please cancel Claims 1-25, without prejudice or disclaimer of subject matter, and add new Claims 26-47 as indicated below. The following is a complete listing of the claims, and replaces all previous versions and listings of claims in the present application.

1.- 25. (Cancelled).

26. (New) A light-emitting diode arrangement, comprising:

at least one light-emitting diode chip;

a multi-layer board having a base of a thermally well conducting material, in particular of metal; and

an electrically insulating and thermally conducting connection layer between an emission surface of the light-emitting diode chip and the board, wherein between the light-emitting chip and the board there is arranged an intermediate carrier separate from those parts with which the light-emitting diode chip is electrically contacted, and wherein the intermediate carrier is formed by an aluminium nitride substrate.

27. (New) The light-emitting diode arrangement according to claim 26,

wherein the electrically insulating connection layer is at least a boundary surface of the light-emitting diode chip which is towards the board.

28. (New) The light-emitting diode arrangement according to claim 26, wherein the electrically insulating connection layer is at least an adhesive layer.

29. (New) The light-emitting diode arrangement according to claim 26, wherein the light-emitting diode chip is accommodated in a depression of the board.

30. (New) The light-emitting diode arrangement according to claim 26, wherein the light-emitting diode chip is arranged in a region of a depression in the base material of the board.

31. (New) The light-emitting diode arrangement according to claim 29, wherein the light-emitting diode chip does not project beyond a contour of the board.

32. (New) The light-emitting diode arrangement according to claim 29, wherein the light-emitting diode chip ends flush with an upper side of the board.

33. (New) The light-emitting diode arrangement according to claim 29, wherein the depression has the function of a reflector.

34. (New) The light-emitting diode arrangement according to claim 29, wherein the walls of the depression are at least partially bevelled.

35. (New) The light-emitting diode arrangement according to claim 26, wherein the light-emitting diode chip is arranged so that the substrate of the light-emitting diode is towards the plate.

36. (New) The light-emitting diode arrangement according to claim 35, wherein the substrate of the light-emitting diode is of an electrically insulating material.

37. (New) The light-emitting diode arrangement according to claim 36, wherein the substrate of the light-emitting diode is formed of sapphire.

38. (New) The light-emitting diode arrangement according to claim 26, wherein the light-emitting diode chip is arranged so that the substrate of the light-emitting diodes is away from the board.

39. (New) The light-emitting diode arrangement according to claim 26, wherein the light-emitting diode chip is arranged on the intermediate carrier by means of a conductive adhesive.

40. (New) The light-emitting diode arrangement according to claim 26, wherein a side of the intermediate carrier towards the board is electrically insulating.

41. (New) The light-emitting diode arrangement according to claim 40, wherein a region of the intermediate carrier towards the light-emitting diode chip has conductive regions.

42. (New) The light-emitting diode arrangement according to claim 26, wherein at least a region of the light-emitting diode chip is covered by a lens in particular a Fresnel lens.

43. (New) The light-emitting diode arrangement according to claim 42, wherein a region between the board and the lens is at least partially filled by a colour conversion material.

44. (New) The light-emitting diode arrangement according to claim 43, wherein the colour conversion material is arranged above and alongside the light-emitting diode chip.

45. (New) The light-emitting diode arrangement according to claim 26, wherein the light emitting diode chip is connected to a circuit board by means of wires, and the circuit board is applied to the board by means of an insulating layer lying therebetween.

46. (New) A Light-emitting diode arrangement, comprising:  
at least one light-emitting diode chip,

a multi-layer board, having a base of a thermally well conducting layer, in particular of metal; and

an electrically insulating and thermally conducting connection layer between an emission surface of the light-emitting diode chip and the board, wherein between the light-emitting chip and the board there is arranged an intermediate carrier separate from those parts with which the light-emitting diode chip is electrically contacted, and wherein a colour conversion material is arranged above and alongside the light-emitting diode chip.

47. (New) A Light-emitting diode arrangement, comprising:

at least one light-emitting diode chip;

a multi-layer board, having a base of a thermally well conducting layer, in particular of metal; and

an electrically insulating and thermally conducting connection layer between an emission surface of the light-emitting diode chip and the board, wherein between the light-emitting chip and the board there is arranged an intermediate carrier separate from those parts with which the light-emitting diode chip is electrically contacted, and wherein the light-emitting diode chip is arranged on the intermediate carrier by means of a conductive adhesive.